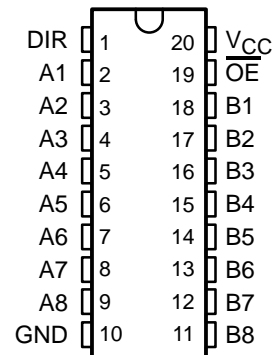# SN74BCT2245
OCTAL TRANSCEIVER AND LINE/MOS DRIVER
WITH 3-STATE OUTPUTS

SCBS102C – FEBRUARY 1992 – REVISED MARCH 2003

- **Operating Voltage Range of 4.5 V to 5.5 V**
- **State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}**
- **B Port Has Equivalent 33-Ω Series Resistors, So No External Resistors Are Required**
- **ESD Protection Exceeds JESD 22**
  - **– 2000-V Human-Body Model (A114-A)**
  - **– 200-V Machine Model (A115-A)**
  - **– 1000-V Charged-Device Model (C101)**

DB, DW, N, OR NS PACKAGE
(TOP VIEW)

DIR	1		20	V_{CC}
A1	2		19	$\overline{OE}$
A2	3		18	B1
A3	4		17	B2
A4	5		16	B3
A5	6		15	B4
A6	7		14	B5
A7	8		13	B6
A8	9		12	B7
GND	10		11	B8

description/ordering information

The SN74BCT2245 octal transceiver and line/ MOS driver is designed for asynchronous communication between data buses.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can disable the devices so that both buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The B-port outputs, which are designed to source or sink up to 12 mA, include 33-Ω series resistors to reduce overshoot and undershoot.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT2245N	SN74BCT2245N
	SOIC – DW	Tube	SN74BCT2245DW	BCT2245
		Tape and reel	SN74BCT2245DWR	
	SOP – NS	Tape and reel	SN74BCT2245NSR	BCT2245
	SSOP – DB	Tape and reel	SN74BCT2245DBR	BA245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Copyright © 2003, Texas Instruments Incorporated

TEXAS INSTRUMENTS

logic diagram (positive logic)

To Seven Other Channels
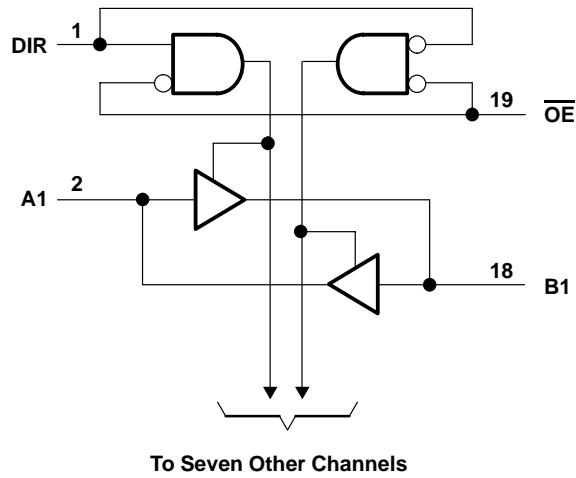
schematic of A-port outputs
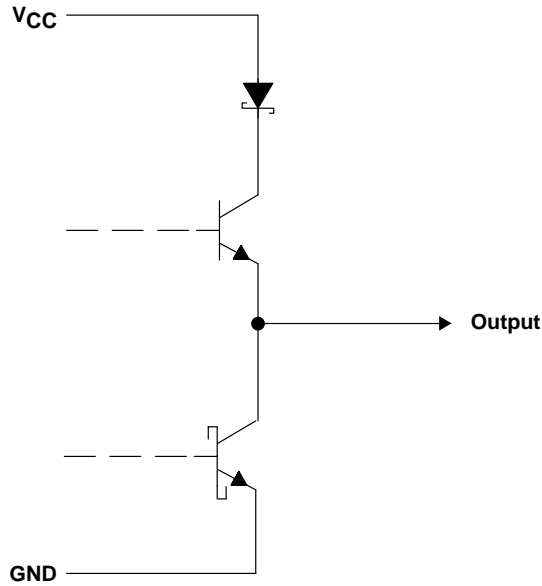
schematic of B-port outputs
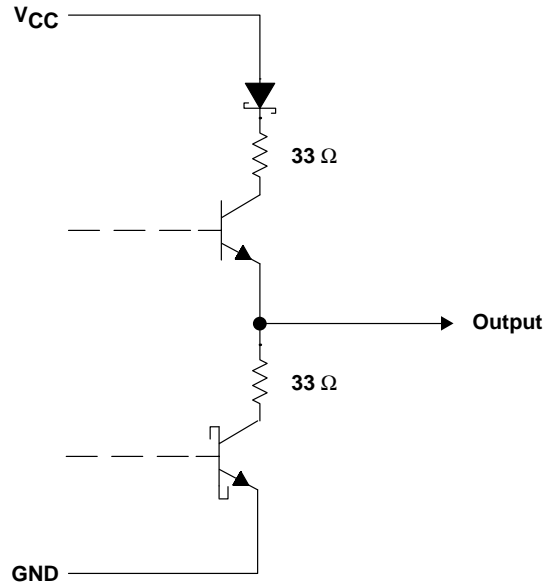
All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O .... −0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O .... −0.5 V to V_{CC}
Input clamp current, I_{IK} .... −30 mA
Current into any output in the low state, I_O .... 60 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package .... 70°C/W
DW package .... 58°C/W
N package .... 69°C/W
NS package .... 60°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{IK}	Input clamp current				−18	mA
I_{OH}	High-level output current	A port			−3	mA
		B port			−12	
I_{OL}	Low-level output current	A port			24	mA
		B port			12	
T_A	Operating free-air temperature		0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}		$V_{CC} = 4.5$ V,	$I_I = -18$ mA			-1.2	V
V_{OH}	A port	$V_{CC} = 4.5$ V	$I_{OH} = -1$ mA	2.5	3.4		V
			$I_{OH} = -3$ mA	2.4	3.3		
	B port	$V_{CC} = 4.5$ V	$I_{OH} = -1$ mA	2.4	3.3		
			$I_{OH} = -12$ mA	2	3.2		
V_{OL}	A port	$V_{CC} = 4.5$ V	$I_{OL} = 24$ mA		0.35	0.5	V
	B port	$V_{CC} = 4.5$ V	$I_{OL} = 1$ mA			0.5	
			$I_{OL} = 12$ mA			0.8	
I_I		$V_{CC} = 5.5$ V,	$V_I = 5.5$ V			0.1	mA
$I_{IH}‡$	A or B port	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			70	μA
	Control input					20	
$I_{IL}‡$		$V_{CC} = 5.5$ V,	$V_I = 0.5$ V			-0.65	mA
$I_{OS}§$	A port	$V_{CC} = 5.5$ V,	$V_O = 0$	-60		-150	mA
	B port			-100		-225	
I_{CCL}	A to B	$V_{CC} = 5.5$ V,	Outputs open		63	100	mA
	B to A				40	64	
I_{CCH}	A to B	$V_{CC} = 5.5$ V,	Outputs open		37	59	mA
	B to A				29	46	
I_{CCZ}	A to B	$V_{CC} = 5.5$ V,	Outputs open		9	15	mA
	B to A				8	14	
C_i	Control input	$V_{CC} = 5$ V,	$V_I = 2.5$ V or 0.5 V		7		pF
C_{io}	A to B	$V_{CC} = 5$ V,	$V_O = 2.5$ V or 0.5 V		9		pF
	B to A				12		

† All typical values are at $V_{CC} = 5$ V, $T_A = 25°C$.
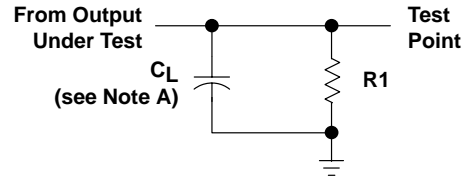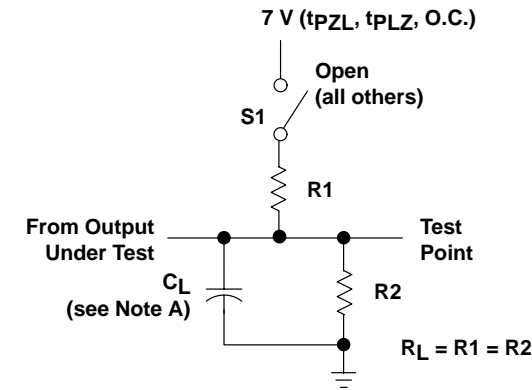‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)
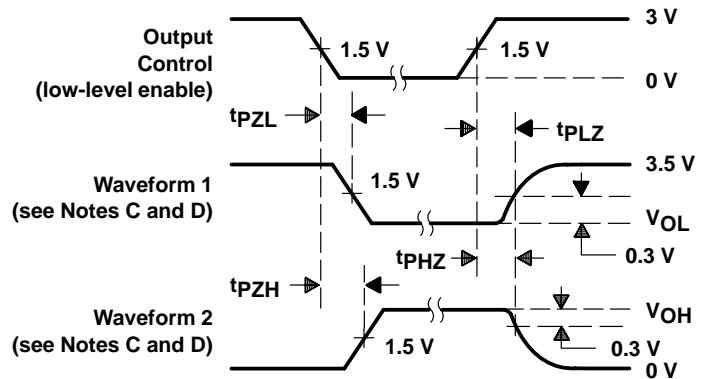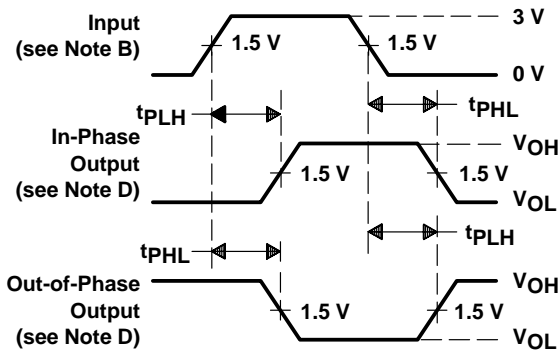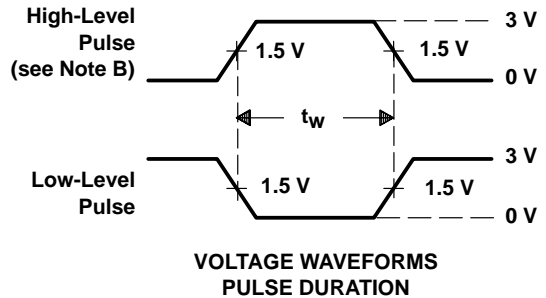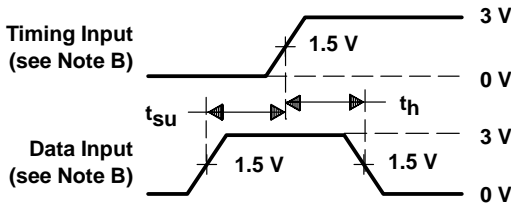
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25°C$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	B	1	3.3	4.9	1	5.8	ns
	B	A	1.7	4.2	6.1	1.7	7	
t_{PHL}	A	B	2.5	5.1	6.9	2.5	7.8	ns
	B	A	2.2	4.7	7.1	2.2	7.7	
t_{PZH}	$\overline{OE}$	B	3.2	6.2	8.6	3.2	9.9	ns
		A	3.8	7.2	9.5	3.8	11.1	
t_{PZL}	$\overline{OE}$	B	5.6	8.3	10.9	5.6	12.2	ns
		A	4.2	7.6	10.1	4.2	11.4	
t_{PHZ}	OE	B	2.6	5.2	7.1	2.6	8.2	ns
		A	3.1	5.7	8	3.1	9.4	
t_{PLZ}	$\overline{OE}$	B	3.5	6	7.9	3.5	9.2	ns
		A	2.3	4.7	6.5	2.3	7.6	

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT FOR
3-STATE AND OPEN-COLLECTOR OUTPUTS

LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $t_r = t_f ≤ 2.5$ ns, duty cycle = 50%.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.
E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74BCT2245DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74BCT2245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT2245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT2245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT2245NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE
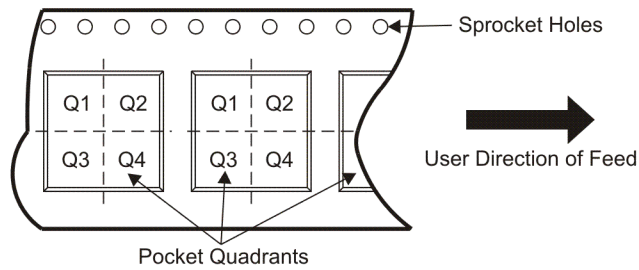
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT2245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74BCT2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74BCT2245NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT2245DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74BCT2245DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74BCT2245NSR	SO	NS	20	2000	346.0	346.0	41.0

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
          D. Falls within JEDEC MO-150

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

	PINS **	14	16	20	24
DIM					
A	MAX	10,50	10,50	12,90	15,30
A	MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DW (R−PDSO−G20)   PLASTIC SMALL−OUTLINE PACKAGE

$\frac{0.512\ (13,00)}{0.496\ (12,60)}$

20   11

$\frac{0.419\ (10,63)}{0.393\ (9,97)}$

$\frac{0.299\ (7,60)}{0.291\ (7,40)}$

Pin 1
Index Area

1   10

0.050 (1,27)

$\frac{0.020\ (0,51)}{0.012\ (0,31)}$

⊕ | 0.010 (0,25) Ⓜ

0.104 (2,65) Max

$\frac{0.012\ (0,30)}{0.004\ (0,10)}$

$\frac{0.013\ (0,33)}{0.008\ (0,20)}$

⌂ | 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)

0°−8°

$\frac{0.050\ (1,27)}{0.016\ (0,40)}$

4040000−4/F 06/2004

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
          D.   Falls within JEDEC MS−013 variation AC.

TEXAS
INSTRUMENTS
www.ti.com

N (R−PDIP−T**)   PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14)

0.045 (1,14) / 0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

0.010 (0,25) M

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

TEXAS INSTRUMENTS
www.ti.com

IMPORTANT NOTICE